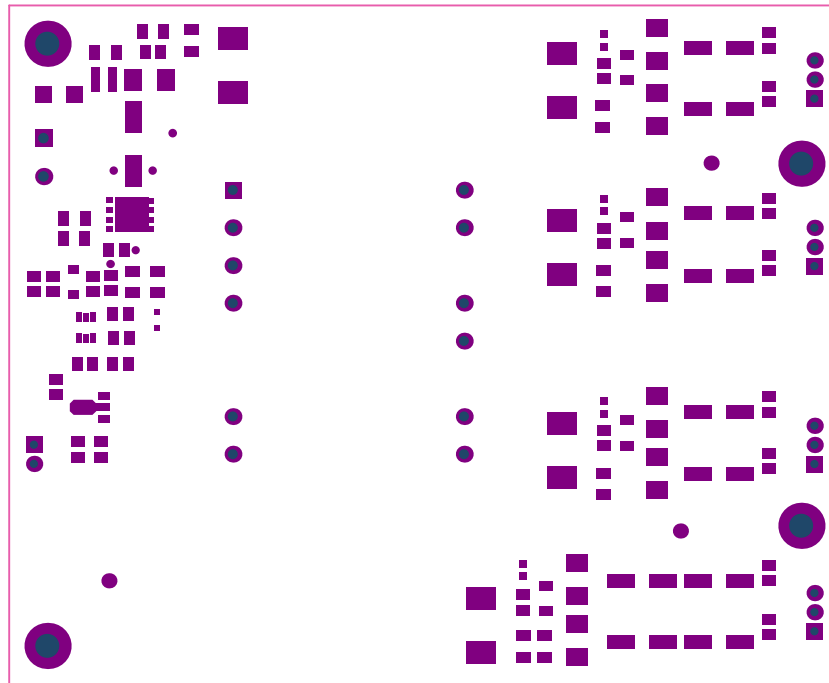
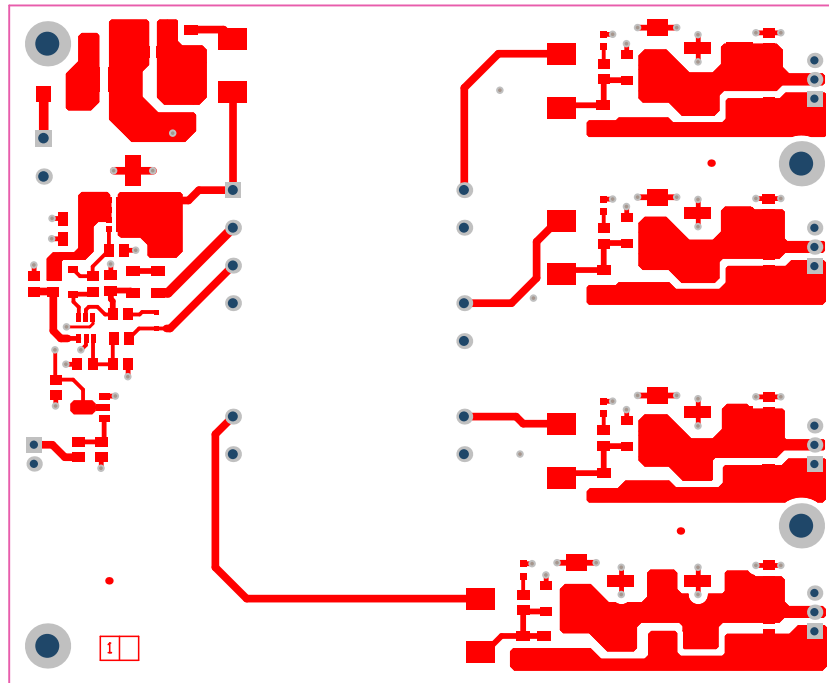


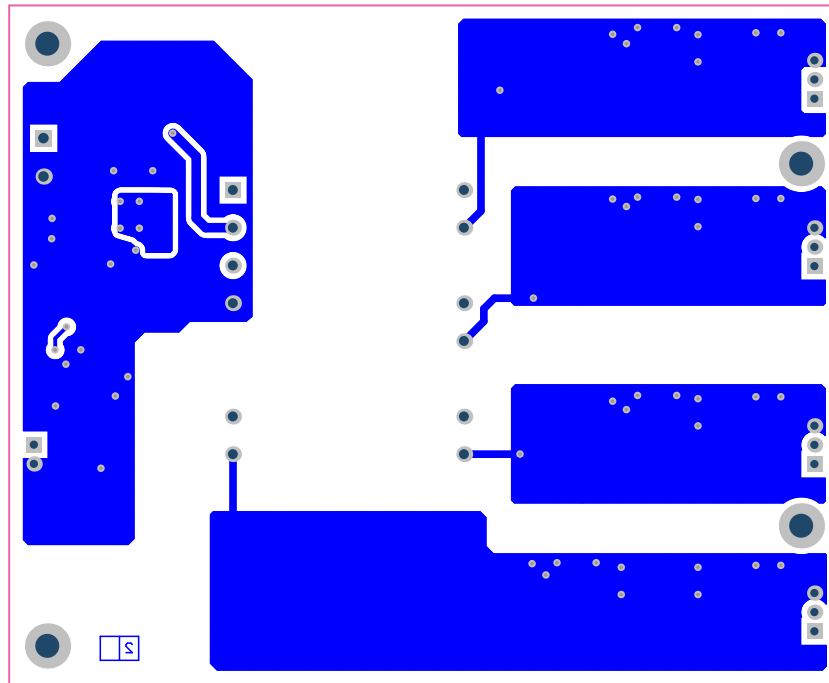
| | | | |
|----------------------------------|----------------------|------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-00182 | REV: E2 | SUN REV: Not In VersionControl |
| LAYER NAME = Top Overlay | | | |
| PLOT NAME = Top Overlay | GENERATED : 7/1/2014 | 3:07:27 PM | TEXAS INSTRUMENTS |



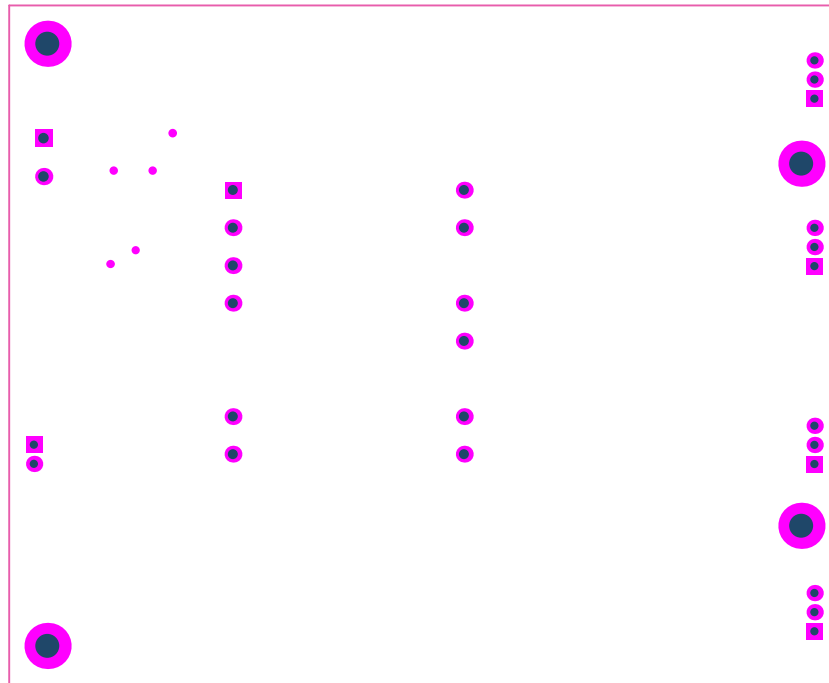
| | | | |
|----------------------------------|---------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-00182 | REV: E2 | SUN REV: Not In VersionControl |
| LAYER NAME = Top Solder | | | |
| PLOT NAME = Top Solder Mask | GENERATED : 7/1/2014 3:07:27 PM | TEXAS INSTRUMENTS | |



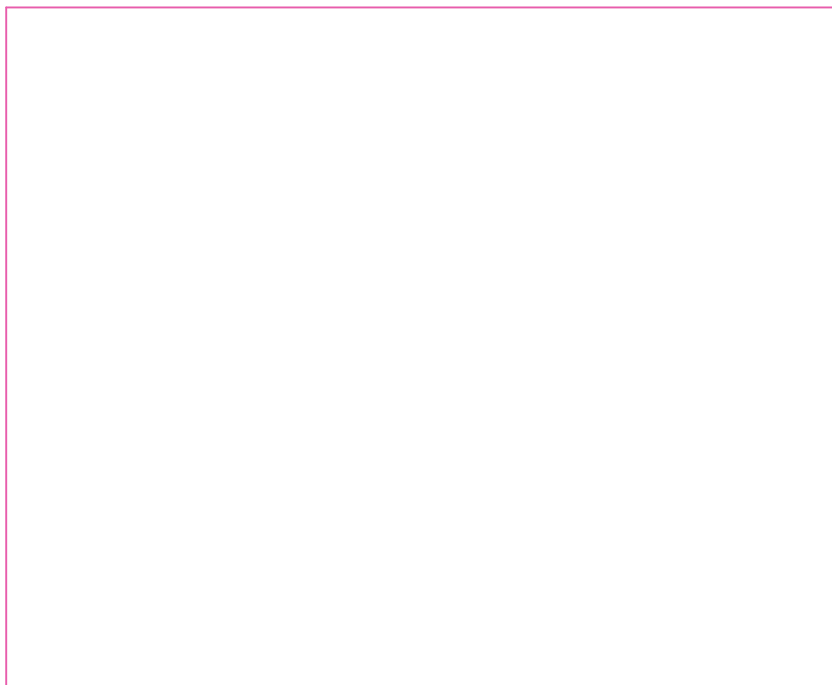
| | | | |
|----------------------------------|---------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-00182 | REV: E2 | SUN REV: Not In VersionControl |
| LAYER NAME = Top Layer | | | |
| PLOT NAME = Top Layer | GENERATED : 7/1/2014 3:07:28 PM | TEXAS INSTRUMENTS | |



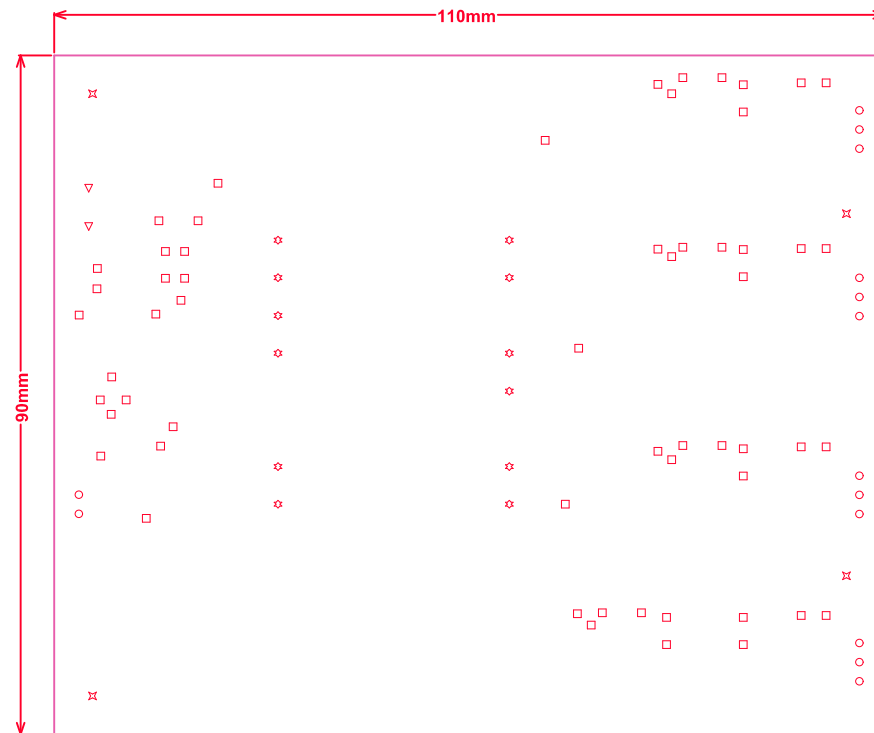
| | | | |
|----------------------------------|---------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-00182 | REV: E2 | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Layer | | | |
| PLOT NAME = Bottom Layer | GENERATED : 7/1/2014 3:07:28 PM | TEXAS INSTRUMENTS | |



| | | | |
|----------------------------------|---------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-00182 | REV: E2 | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Solder | | | |
| PLOT NAME = Bottom Solder Mask | GENERATED : 7/1/2014 3:07:29 PM | TEXAS INSTRUMENTS | |



| | | | |
|----------------------------------|---------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-00182 | REV: E2 | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Overlay | | | |
| PLOT NAME = Bottom Overlay | GENERATED : 7/1/2014 3:07:29 PM | TEXAS INSTRUMENTS | |



| Symbol | Hit Count | Tool Size | Plated | Hole Type |
|--------|-----------|--------------------|--------|-----------|
| □ | 57 | 20mil (0.508mm) | PTH | Round |
| ○ | 14 | 44mil (1.118mm) | PTH | Round |
| ☆ | 12 | 53mil (1.346mm) | PTH | Round |
| ▽ | 2 | 55.118mil (1.4mm) | PTH | Round |
| ✕ | 4 | 125.984mil (3.2mm) | PTH | Round |
| | 89 Total | | | |

Drill Table
 DRILL TOLERANCE
 FOR PTH +/- 3MIL

| | | | |
|----------------------------------|----------------------|------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-00182 | REV: E2 | SUN REV: Not In VersionControl |
| LAYER NAME = Drill Drawing | | | |
| PLOT NAME = Drill Drawing | GENERATED : 7/1/2014 | 3:07:30 PM | TEXAS INSTRUMENTS |

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